

**Amendments to the Claims:**

This listing of claims will replace all prior versions, and listings, of claims in the application:

**IN THE CLAIMS:**

1. (currently amended)      A modeling compound comprising, in combination, a polyvinyl chloride resin comprising 40-60% of the compound by weight;  
a primary plasticizer comprising 20-25% of the compound by weight;  
an epoxidized soybean oil secondary plasticizer comprising 1-3% of the compound by weight;  
a heat stabilizer comprising zinc comprising 1-2% of the compound by weight;  
dry expanded microspheres;  
glass microspheres; and  
a rheology modifier comprising a thixotropic agent comprising an organic filler, wherein the modeling compound comprises .3% or less of water, and wherein said compound is a putty-like, maleable compound at room temperature and retains a desired shape at temperatures from room temperature up to 275 °F.
2. (canceled)
3. (original) A modeling compound as in claim 1 where said primary plasticizer comprises a monomeric plasticizer.
4. (original) A modeling compound as in claim 1 where said primary plasticizer comprises a polymeric plasticizer.
5. (previously presented)      A modeling compound as in claim 1 where said zinc heat stabilizer comprises metal ion which complexes with HCL.
6. (canceled)
7. (canceled)

8. (canceled)

9. (previously presented) A modeling compound comprising, in combination,

40% - 60% polyvinyl chloride by weight of the compound;

20% - 25% primary plasticizer by weight of the compound;

1% - 3% epoxidized soybean oil secondary plasticizer by weight of the compound;

1% - 2% zinc stabilizer by weight of the compound;

15% - 25% dry expanded microspheres and glass microspheres by weight of the compound; and

1% - 3% thixotropic agent by weight of the compound comprising an organic filler rheology modifier, wherein the modeling compound comprises 0.3% or less of water, and wherein said compound is a putty-like, malleable compound at room temperature and retains a desired shape at temperatures from room temperature up to 275 °F.

10. (original) A modeling compound as in claim 9 where said polyvinyl chloride comprises 48.8% by weight of the compound.

11. (original) A modeling compound as in claim 9 where said primary plasticizer comprises a monomeric plasticizer.

12. (original) A modeling compound as in claim 9 where said primary plasticizer comprises a polymeric plasticizer.

13. (original) A modeling compound as in claim 9 where said primary plasticizer comprises 20.7% by weight of the compound.

14. (previously presented) A modeling compound as in claim 9 where said epoxidized soybean oil secondary plasticizer comprises 1.2% by weight of the compound.

15. (previously presented) A modeling compound as in claim 9 where said zinc stabilizer comprises metal ion which complexes with HCL.

16. (previously presented) A modeling compound as in claim 9 where said zinc stabilizer comprises 1.2% by weight of the compound.

17. (canceled)

18. (original) A modeling compound as in claim 9 where said microspheres comprise 26.4% by weight of the compound.

19. (original) A modeling compound as in claim 9 where said thixotropic agent comprises 1.8% by weight of the compound.

20. (canceled).

21. (canceled)

22. (canceled)

23. (canceled)

24. (canceled)

25. (canceled)

26. (canceled)

27. (canceled)

28. (canceled)

29. (canceled)

30. (canceled)

31. (canceled)

32. (canceled)

33. (previously presented) The modeling compound of claim 1, wherein the heat stabilizer comprising zinc is calcium zinc.

34. (canceled)

35. (previously presented) The modeling compound of claim 9, wherein the zinc stabilizer is calcium zinc.

36. (previously presented) The modeling compound of claim 15, wherein the zinc stabilizer is calcium zinc.

37. (previously presented) The modeling compound of claim 16, wherein the zinc stabilizer is calcium zinc.

38. (canceled)

39. (canceled)